IXYS

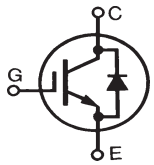
GenX3™ 600V IGBTs w/ Diode

IXGA30N60C3D4*
IXGP30N60C3D4

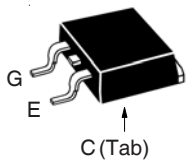
*Obsolete Part Number

V_{CES} = 600V
I_{C110} = 30A
$V_{CE(sat)}$ ≤ 3.0V
$t_{fi(typ)}$ = 47ns

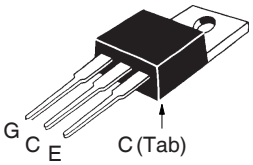
High-Speed PT IGBTs for 40-100kHz Switching



TO-263 AA (IXGA)



TO-220AB (IXGP)



Symbol	Test Conditions	Maximum Ratings	
V_{CES}	T_C = 25°C to 150°C	600	V
V_{CGR}	T_J = 25°C to 150°C, R_{GE} = 1MΩ	600	V
V_{GES}	Continuous	± 20	V
V_{GEM}	Transient	± 30	V
I_{C25}	T_C = 25°C	60	A
I_{C110}	T_C = 110°C	30	A
I_{CM}	T_C = 25°C, 1ms	150	A
SSOA (RBSOA)	V_{GE} = 15V, T_{VJ} = 125°C, R_G = 5Ω Clamped Inductive Load	I_{CM} = 60 @ ≤ V_{CES}	A
P_C	T_C = 25°C	220	W
T_J		-55 ... +150	°C
T_{JM}		150	°C
T_{stg}		-55 ... +150	°C
T_L	1.6mm (0.062 in.) from Case for 10s	300	°C
T_{SOLD}	Plastic Body for 10 seconds	260	°C
M_d	Mounting Torque (TO-220)	1.13/10	Nm/lb.in.
Weight	TO-220 TO-263	2.5 3.0	g g

G = Gate D = Collector
S = Emitter Tab = Collector

Features

- Optimized for Low Switching Losses
- Square RBSOA
- Anti-Parallel Ultra Fast Diode
- International Standard Packages

Advantages

- High Power Density
- Low Gate Drive Requirement

Applications

- Power Inverters
- UPS
- Motor Drives
- SMPS
- PFC Circuits
- Battery Chargers
- Welding Machines
- Lamp Ballasts
- High Frequency Power Inverters

Symbol	Test Conditions (T_J = 25°C Unless Otherwise Specified)	Characteristic Values Min.	Typ.	Max.	
BV_{CES}	I_C = 250μA, V_{GE} = 0V	600			V
$V_{GE(th)}$	I_C = 250μA, V_{CE} = V_{GE}	4.0		5.5	V
I_{CES}	V_{CE} = V_{CES}, V_{GE} = 0V			75	μA
	T_J = 125°C			500	μA
I_{GES}	V_{CE} = 0V, V_{GE} = ± 20V			±100	nA
$V_{CE(sat)}$	I_C = 20A, V_{GE} = 15V, Note 1		2.6	3.0	V
	T_J = 125°C		1.8		V

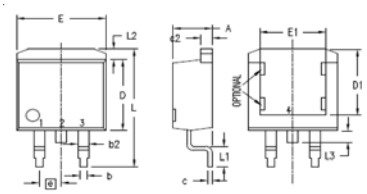
Symbol	Test Conditions (T_J = 25°C Unless Otherwise Specified)	Characteristic Values Min.	Typ.	Max.	
g_{fs}	I_C = 20A, V_{CE} = 10V, Note 1	9	16		S
C_{ies}	V_{CE} = 25V, V_{GE} = 0V, f = 1MHz		915		pF
C_{oes}			78		pF
C_{res}			32		pF
Q_g	I_C = 20A, V_{GE} = 15V, V_{CE} = 0.5 • V_{CES}		38		nC
Q_{ge}			8		nC
Q_{gc}			17		nC
$t_{d(on)}$	**Inductive Load, T_J = 25°C** I_C = 20A, V_{GE} = 15V V_{CE} = 300V, R_G = 5Ω		16		ns
t_{ri}			26		ns
E_{on}			0.27		mJ
$t_{d(off)}$			42	75	ns
t_{fi}			47		ns
E_{off}			0.09	0.18	mJ
$t_{d(on)}$	**Inductive Load, T_J = 125°C** I_C = 20A, V_{GE} = 15V V_{CE} = 300V, R_G = 5Ω		17		ns
t_{ri}			28		ns
E_{on}			0.44		mJ
$t_{d(off)}$			70		ns
t_{fi}			90		ns
E_{off}			0.33		mJ
R_{thJC}				0.56	°C/W
R_{thCS}	TO-220		0.50		°C/W

Reverse Diode (FRED)

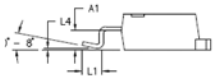
Symbol	Test Conditions (T_J = 25°C, Unless Otherwise Specified)		Characteristic Values Min.	Typ.	Max.	
V_F	I_F = 10A, V_{GE} = 0V, Note 1				3.0	V
		T_J = 150°C		1.7		V
t_{rr}	I_F = 10A, -di_F/dt = 200A/μs V_R = 300V	T_J = 100°C		60		ns
I_{RM}		T_J = 25°C			3	A
		T_J = 100°C			4	A
R_{thJC}					2.5	°C/W

Note 1: Pulse test, t ≤ 300μs, duty cycle, d ≤ 2%.

TO-263 Outline

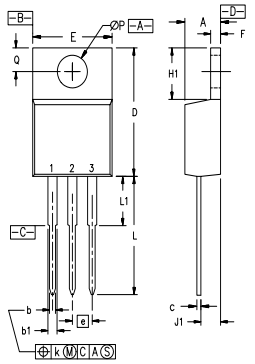


1 = Gate
2 = Collector
3 = Emitter
4 = Collector



SYM	INCHES MIN	INCHES MAX	MILLIMETERS MIN	MILLIMETERS MAX
A	.160	.190	4.06	4.83
A1	.080	.110	2.03	2.79
b	.020	.039	0.51	0.99
b2	.045	.055	1.14	1.40
c	.016	.029	0.40	0.74
c2	.045	.055	1.14	1.40
D	.340	.380	8.64	9.65
D1	.315	.350	8.00	8.89
E	.380	.410	9.65	10.41
E1	.245	.320	6.22	8.13
e	.100 BSC		2.54 BSC	
L	.575	.625	14.61	15.88
L1	.090	.110	2.29	2.79
L2	.040	.055	1.02	1.40
L3	.050	.070	1.27	1.78
L4	0	.005	0	0.13

TO-220 Outline



1 = Gate 2 = Collector
3 = Emitter

SYM	INCHES MIN	INCHES MAX	MILLIMETERS MIN	MILLIMETERS MAX
A	.170	.190	4.32	4.83
b	.025	.040	0.64	1.02
b1	.045	.065	1.15	1.65
c	.014	.022	0.35	0.56
D	.580	.630	14.73	16.00
E	.390	.420	9.91	10.66
e	.100 BSC		2.54 BSC	
F	.045	.055	1.14	1.40
H1	.230	.270	5.85	6.85
J1	.090	.110	2.29	2.79
k	0	.015	0	0.38
L	.500	.550	12.70	13.97
L1	.110	.230	2.79	5.84
ØP	.139	.161	3.53	4.08
Q	.100	.125	2.54	3.18

Fig. 1. Output Characteristics @ T_J = 25ºC

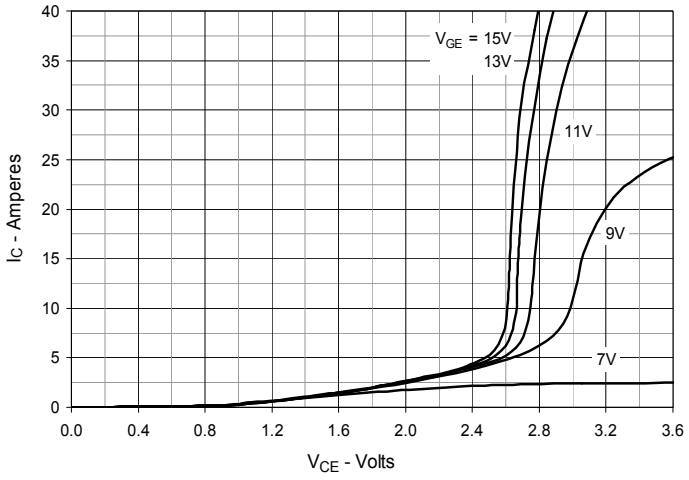


Fig. 2. Extended Output Characteristics @ T_J = 25ºC

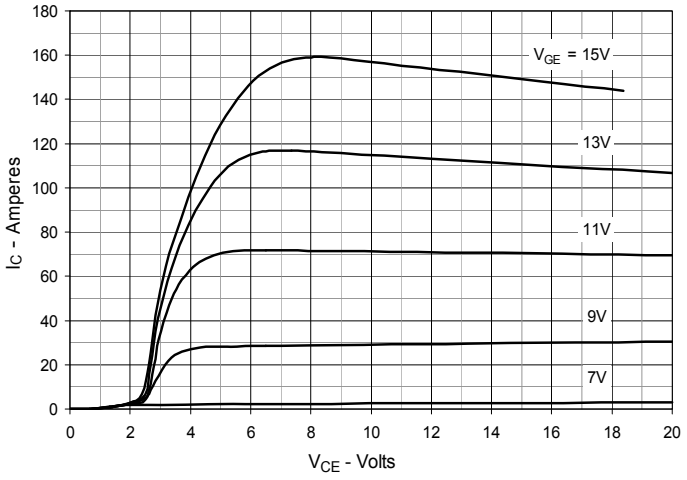


Fig. 3. Output Characteristics @ T_J = 125ºC

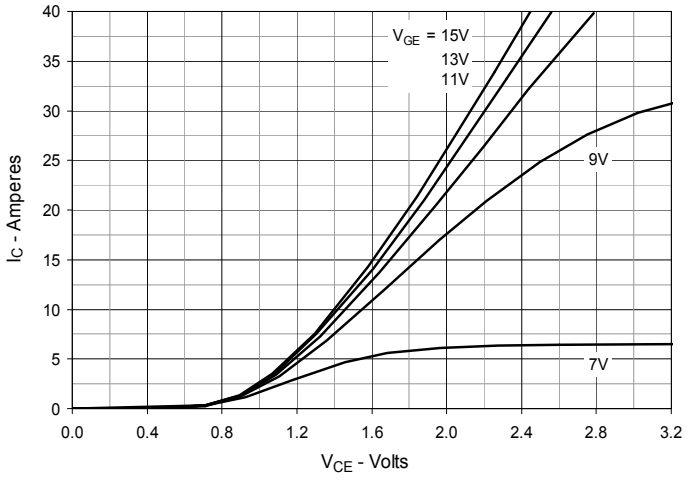


Fig. 4. Dependence of $V_{CE(sat)}$ on JunctionTemperature

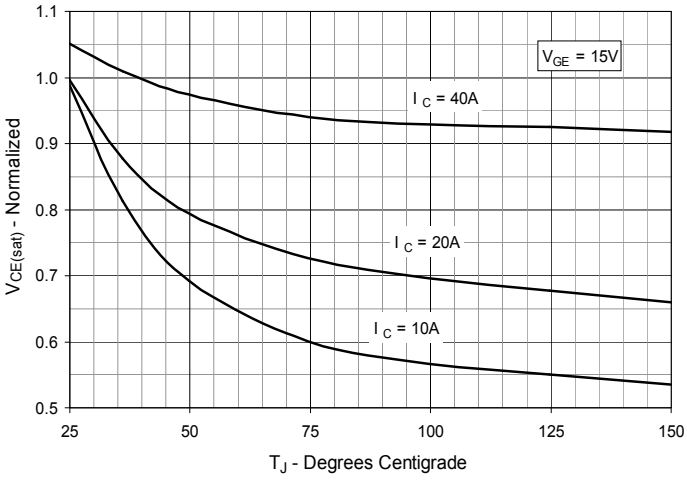


Fig. 5. Collector-to-Emitter Voltage vs. Gate-to-Emitter Voltage

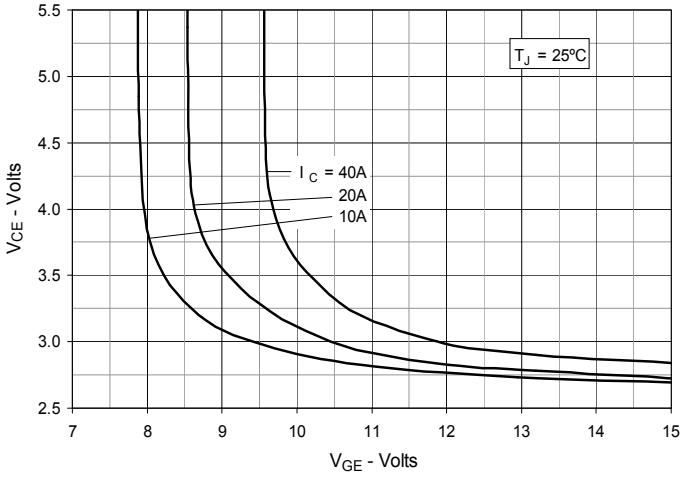


Fig. 6. Input Admittance

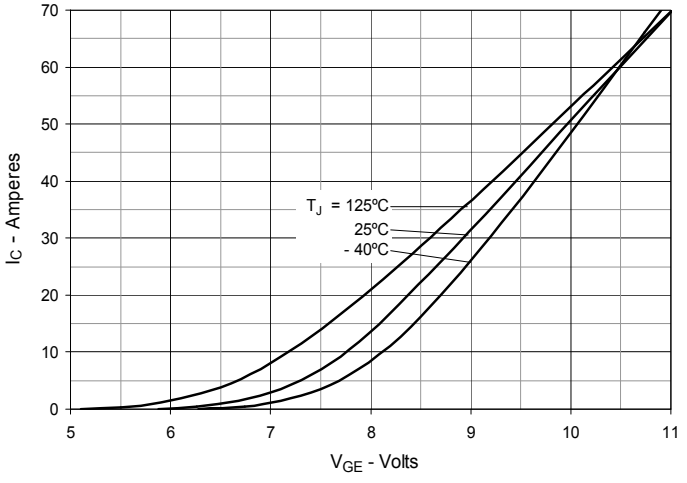


Fig. 7. Transconductance

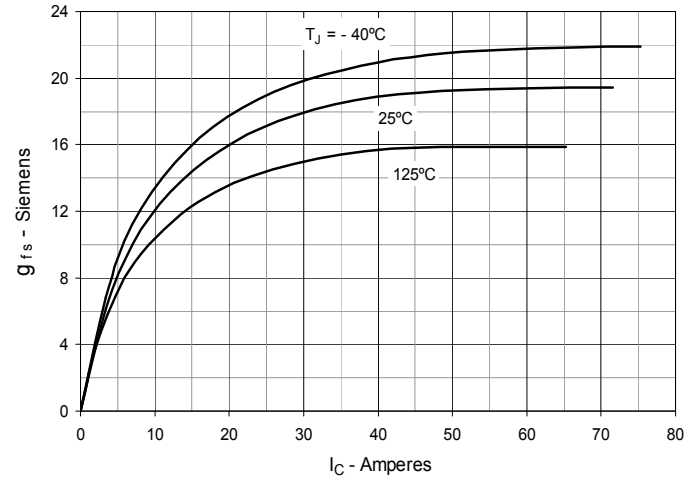


Fig. 8. Gate Charge

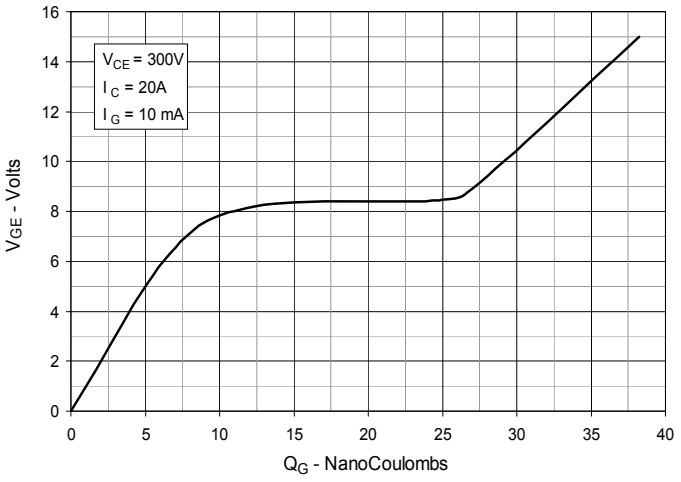


Fig. 9. Capacitance

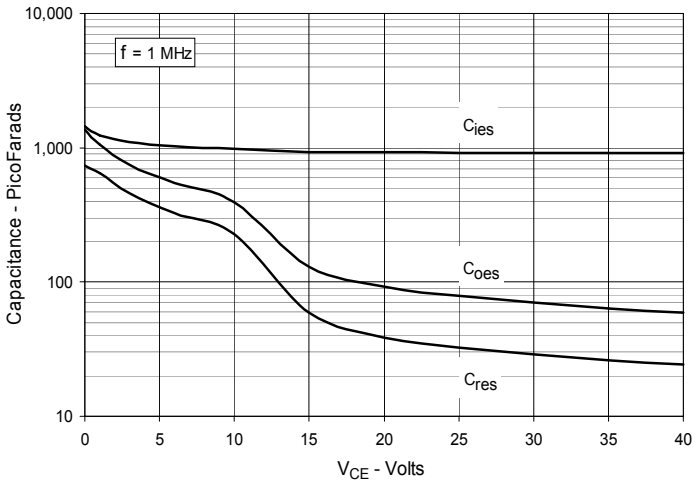


Fig. 10. Reverse-Bias Safe Operating Area

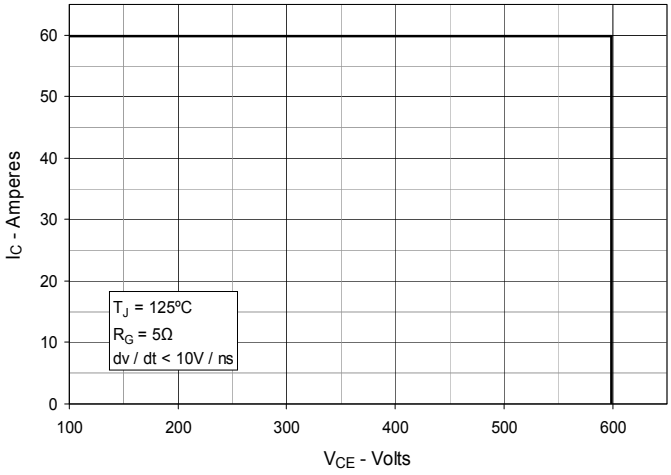


Fig. 11. Maximum Transient Thermal Impedance

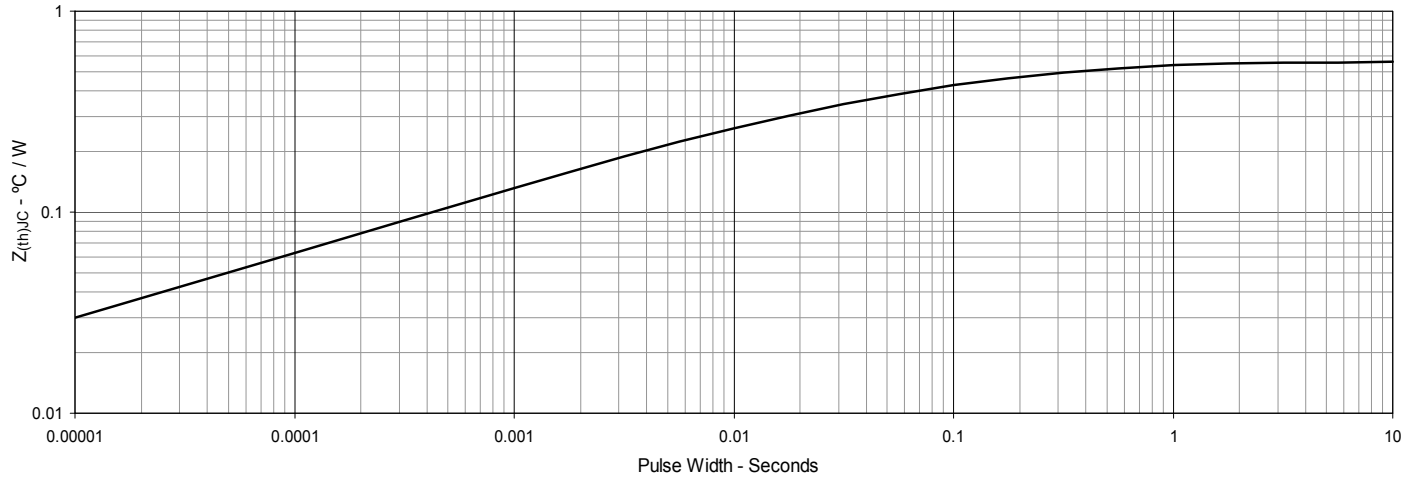


Fig. 12. Inductive Switching Energy Loss vs. Gate Resistance

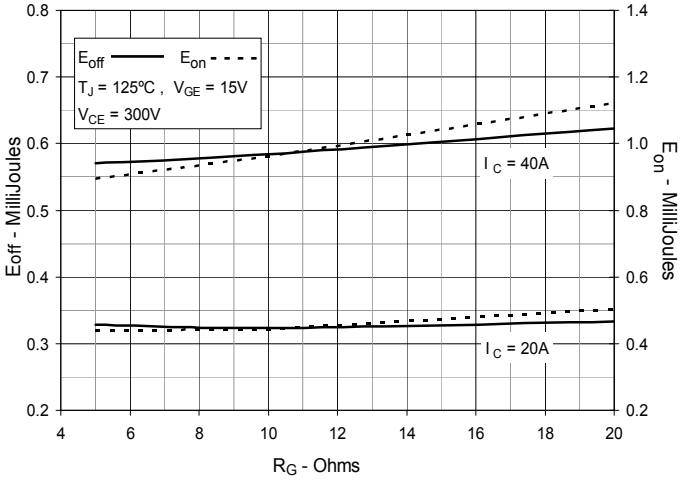


Fig. 13. Inductive Switching Energy Loss vs. Collector Current

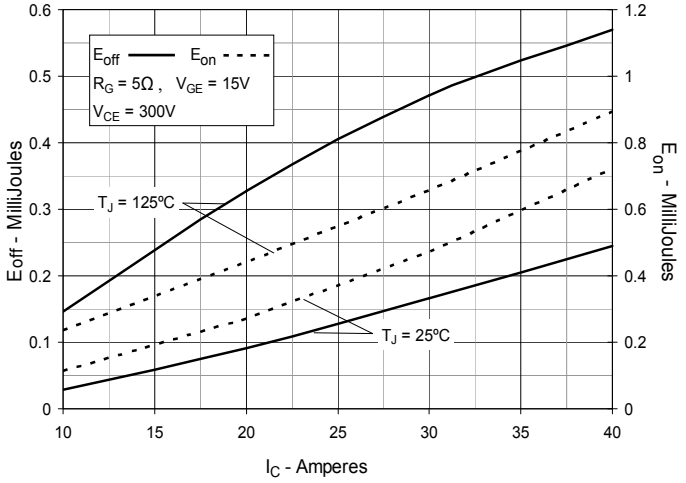


Fig. 14. Inductive Switching Energy Loss vs. Junction Temperature

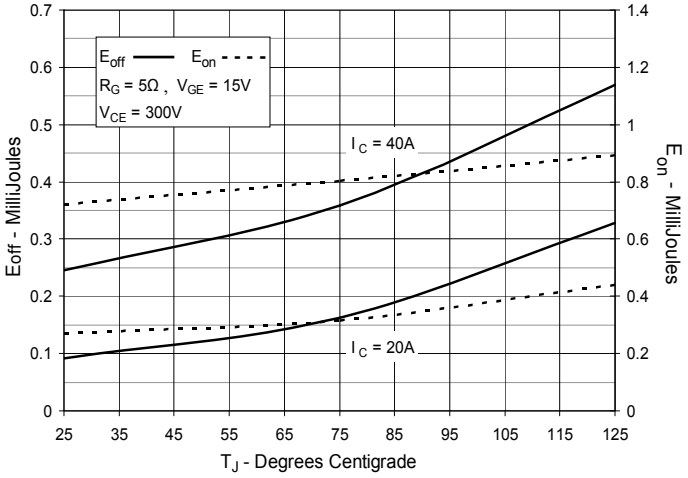


Fig. 15. Inductive Turn-off Switching Times vs. Gate Resistance

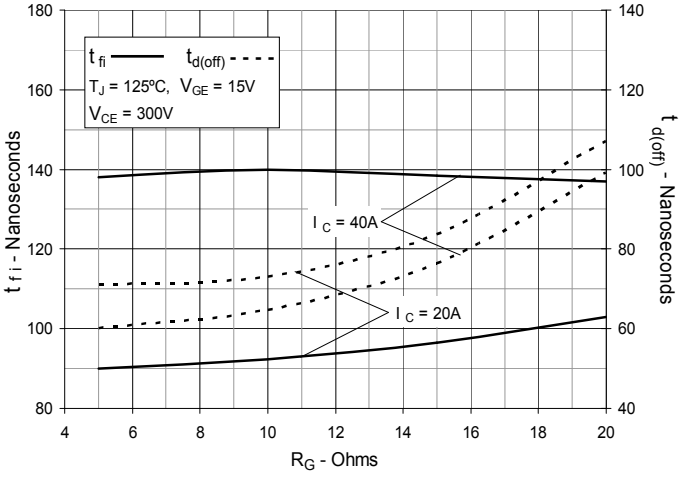


Fig. 16. Inductive Turn-off Switching Times vs. Collector Current

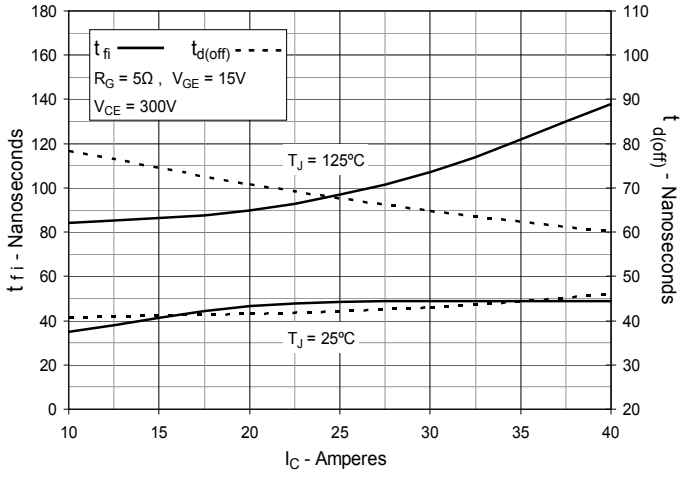


Fig. 17. Inductive Turn-off Switching Times vs. Junction Temperature

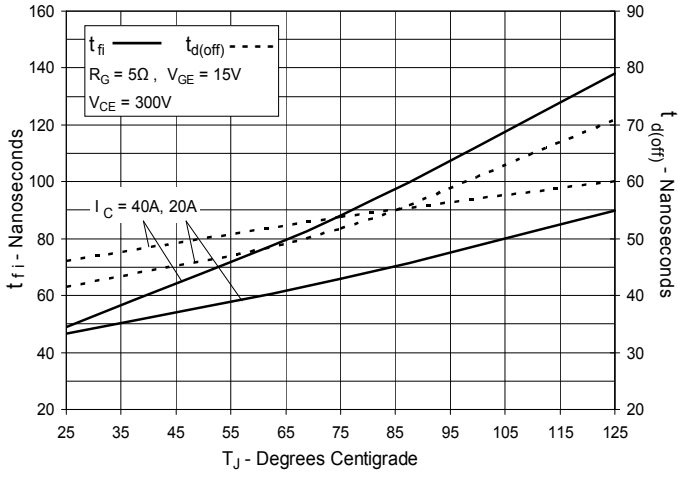


Fig. 18. Inductive Turn-on Switching Times vs. Gate Resistance

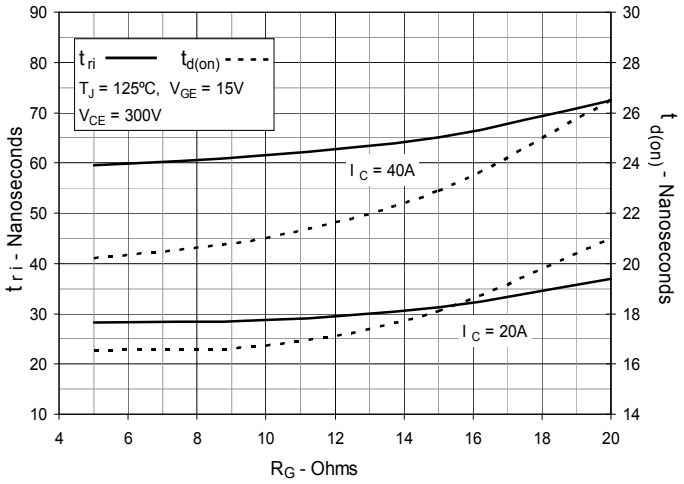


Fig. 19. Inductive Turn-on Switching Times vs. Collector Current

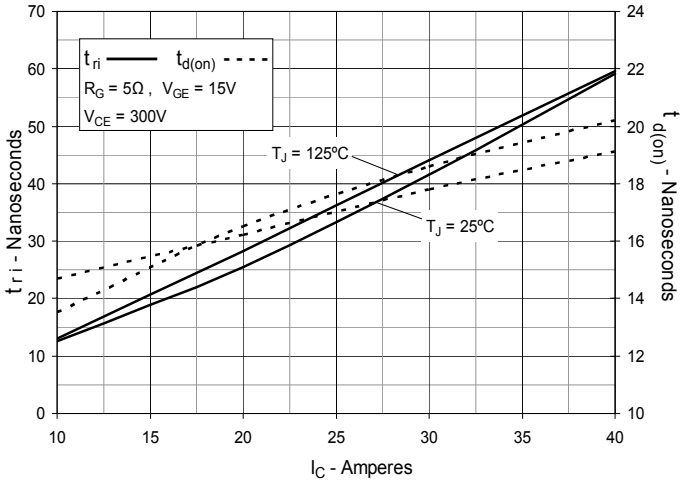
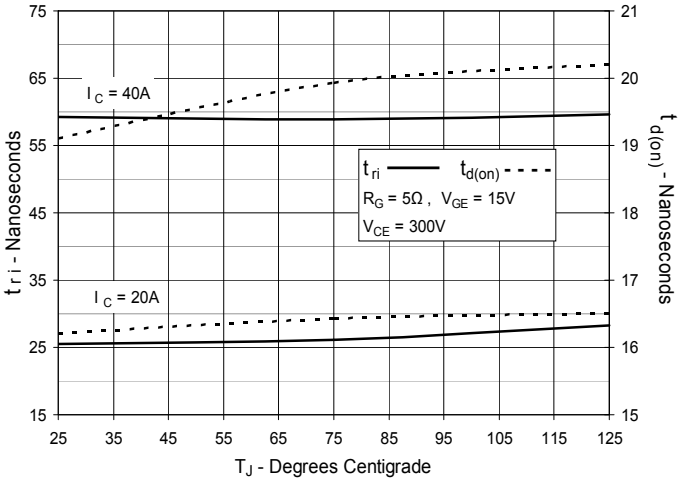


Fig. 20. Inductive Turn-on Switching Times vs. Junction Temperature



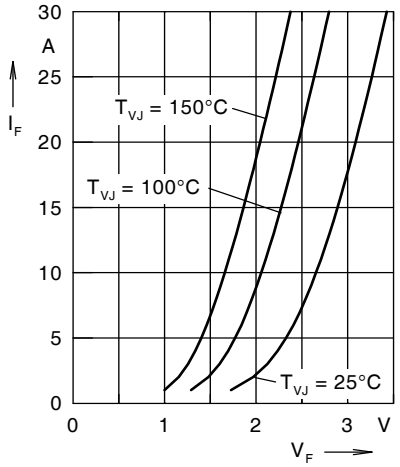


Fig. 21. Forward current I_F versus V_F

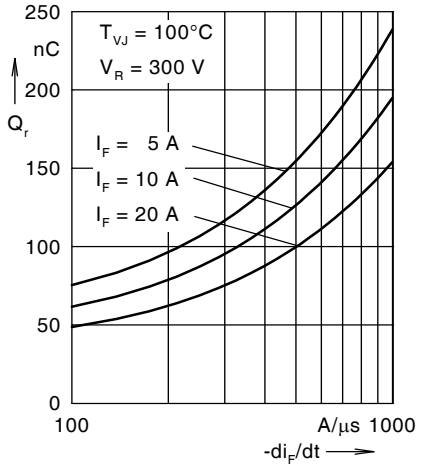


Fig. 22. Reverse recovery charge Q_r

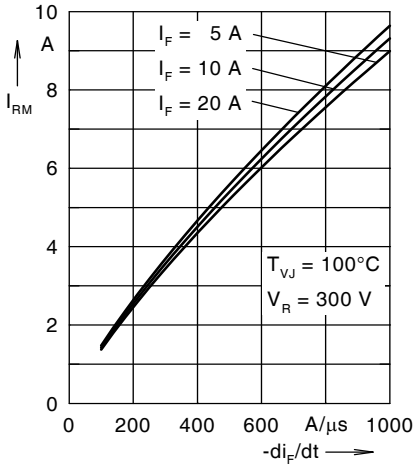


Fig. 23. Peak reverse current I_{RM}

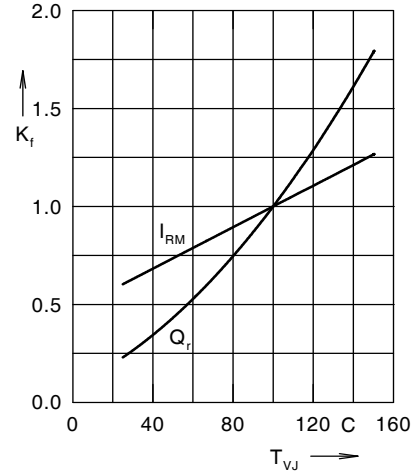


Fig. 24. Dynamic parameters Q_r, I_{RM}

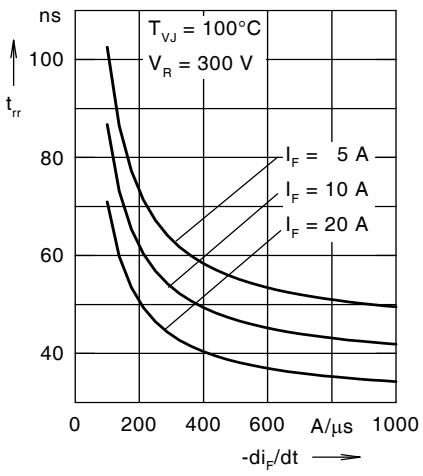


Fig. 25. Recovery time t_{rr} versus $-di_F/dt$

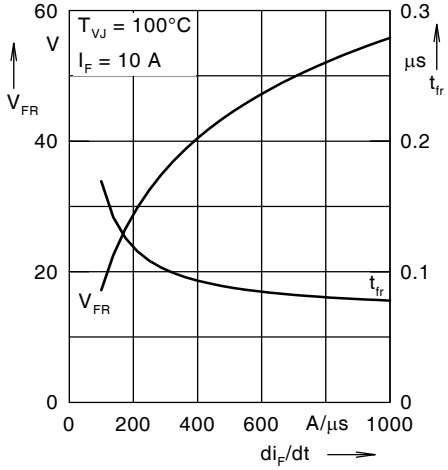


Fig. 26. Peak forward voltage V_{FR} and

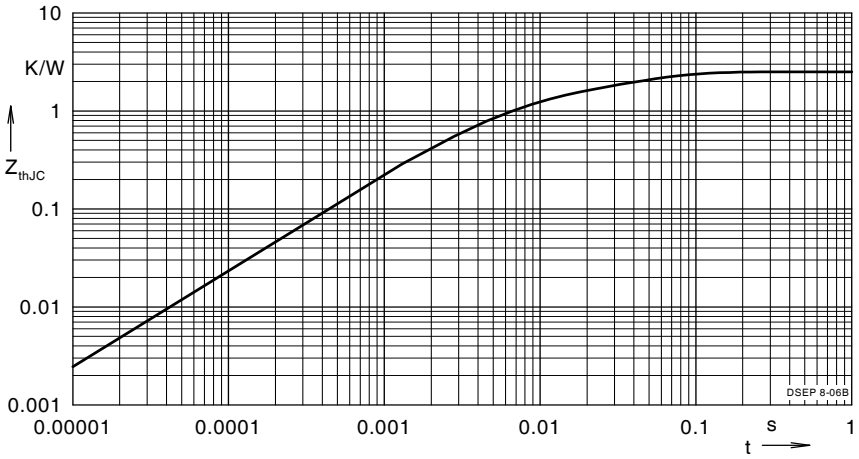


Fig. 27. Transient thermal resistance junction-to-case

NOTE: Fig. 2 to Fig. 6 shows typical values